



SOT136-3

plastic, small outline; leaded package; 28 terminals; 1.27 mm pitch; 7.5 mm x 17.92 mm x 2.35 mm body

13 December 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO
Package type industry code	SO28
Package style descriptive code	SO (small outline)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-7-2016
Manufacturer package code	98ASB42345B

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	17.8	-	17.92	19.05	mm
E	package width	7.4	-	7.5	7.6	mm
A	seated height	2.35	-	2.5	2.65	mm
e	nominal pitch	-	-	1.27	-	mm
n ₂	actual quantity of termination	-	-	28	-	



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2. Package outline

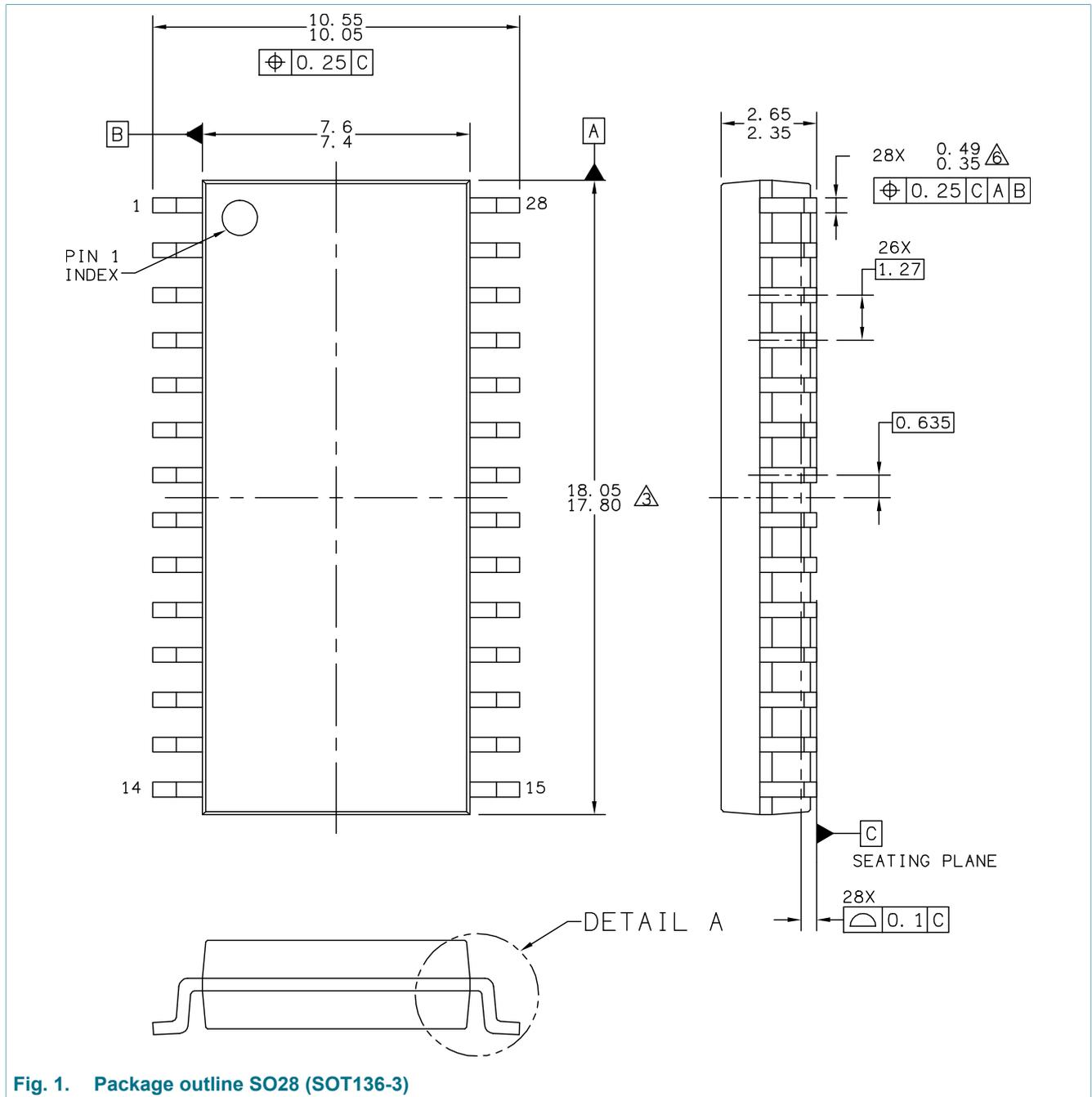


Fig. 1. Package outline SO28 (SOT136-3)

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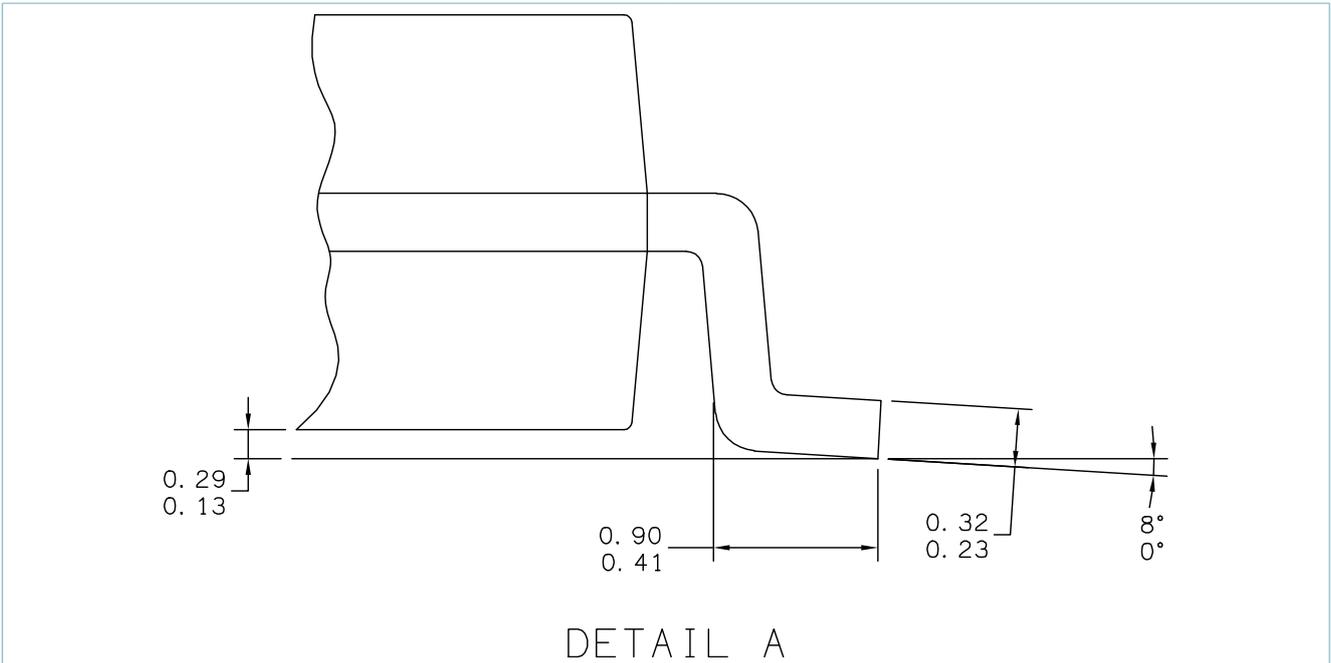


Fig. 2. Package outline dt1 SO28 (SOT136-3)

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
4. 751F-01 THRU -04 OBSOLETE. NEW STANDARD: 751F-05
5. THIS DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSION ALLOWABLE DAM BAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THIS DIMENSION AT MAXIMUM MATERIAL CONDITION.

Fig. 3. Package outline note SO28 (SOT136-3)

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3. Legal information

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